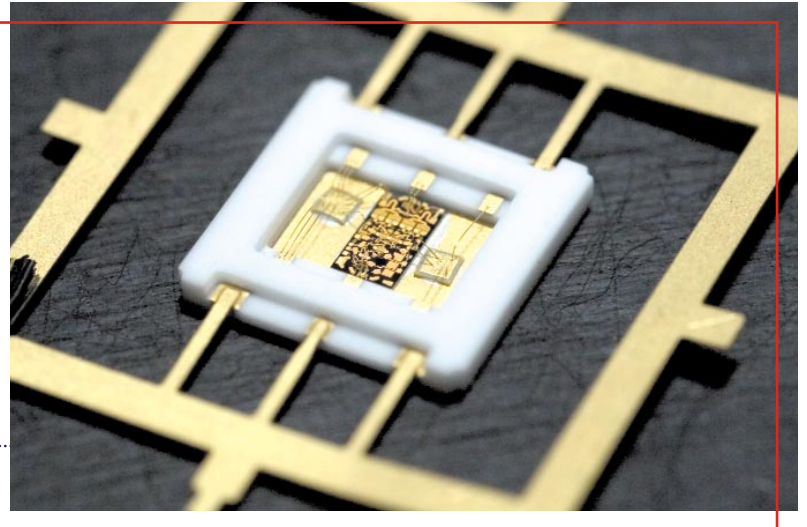


Advanced Packaging Assembly Services



Criteria Labs provides world-class advanced packaging assembly services to meet all your design requirements. We can take you from prototype design to high-volume production. Whether you have a simple monolithic process, high-technology mix, chip on board with surface mount technology or complex multi-chip or opto assemblies, Criteria Labs can meet all your assembly specifications.

Engineering:

Criteria Labs has assembled world-class design and engineering teams to solve your complex problems.

TURNKEY

- > Product engineering
- > Program management
- > Advanced interconnect development
- > Packaging and development of interconnection technologies
- > Process development for advanced technology
- > Qualification plan development
- > Construction analysis
- > Semiconductor failure analysis

SOFTWARE

- > Characterization and validation of new silicon (digital, mixed signal, discrete components, i.e. transistors, diodes and RF)
- > Test plan and design for testability, probe and final test (digital, mixed signal, discrete components, i.e. transistors, diodes and RF)
- > Test analysis for yield improvement

- > Test analysis for test time reduction
- > Conversion between different ATE platforms (digital and mixed signal)

HARDWARE

- > Probe card design including spider
- > Load board design (low frequency to high frequency)
- > Burn-in
- > DUT/probe interface boards
- > Tape pocket design (for tape & reel services)
- > Handler kit/interface

PROCESS ENGINEERING FOR MICROELECTRONIC PACKAGING

- > Hybrids
- > Chip on board designs (COB)
- > Advanced packaging
- > Flex boards
- > Smart cards

ADVANCED PACKAGING ASSEMBLY SERVICES

Services:

Criteria Labs provides a broad array of in-house services to reduce your time to market, verify quality and make sure what's being shipped meets your exact specifications

WAFER TEST, FINAL TEST and TEST ENGINEERING SERVICES

- > Wafer probe from -55° C to +175° C
- > Off line inking
- > Final semiconductor package electric test -55° C to +175° C
- > Wafer mapping
- > Data logging and yield monitoring with feedback to customer
- > Laser marking
- > Package inspection

DIE PROCESSING

- > Wafer saw (2" to 8")
- > Wafer sort
- > Visual inspection (*MIL-STD 883 Method 2010 A or B*)
- > Die mapping
- > Wafer wash/ink removal
- > Die sort duals, trios and quads
- > Die to waffle pack/GEL pack
- > Die to tape
- > Bar code labels
- > Special packing

PACKAGING

COMMERCIAL, MEDICAL CUSTOM, CERAMIC AND PROTOTYPE

- > Ceramic dips, flat packs, LCC, CERQUAD, CERPAC, ceramic SOIC
- > BGA, CQFP, CPGA, TO-CAN, METAL CAN
- > Sidebrazed, JLCC
- > Multi chip module (MCM), hybrids, chip on board (COB)
- > Flex assembly, smart cards, FR4 chip bonding

- > MIMS assembly
- > Opto assembly
- > Die attach material
 - Silver glass: QMI 2569 conductive
 - Silver-filled cyanate ester: JM-7000 and QMI-84-1 or 3 (conductive or nonconductive)
 - Silver-filled epoxy
 - Electrically insulating epoxy
 - Low-temp cure epoxies
 - Eutectic:
 - ~ 2% silicon 98% gold preform
 - ~ 80% gold 20% tin preform
- > Sealing and encapsulation
 - Solder sealing (gold-tin eutectic) and glass sealing
 - Resistance welding for metal cans
 - Glob topping with hysol material on custom packages
 - Seam seal
 - Taped lids
 - B-stage epoxy attachment
- > Assembly testing (quality conforms or exceeds military requirements)
 - Die shear strength
 - Bond pull
 - Non-destructive bond pull (Class S)
 - Fine and gross leak testing
 - Constant acceleration (centrifuge)
 - Solderability
 - Temperature cycle
 - Resistance to solvents
 - External visual
- > Lab suitability qualification services
 - Solder dip
 - Lead trim and form/manual
 - Lead inspection and repair
 - Temperature cycle
 - Constant acceleration (centrifuge)
 - Fine and gross leak

- Resistance to solvents testing
- Marking
- Demark and remark
- Ball shear
- Bond pull
- Die shear

PRODUCT ASSEMBLY QUALIFICATION

- > Environmental Tests
 - Steady state life test *(Method 1005)*
 - Thermal shock *(Method 1011)*
 - Temp cycling *(Method 1010)*
 - Burn-in *(Method 1015)*
 - Moisture resistance *(Method 1004)*
 - Fine/gross leak testing *(Method 1014)*
 - Internal water vapor content (RGA)
(Method 1018)
 - Salt atmosphere corrosion *(Method 1009)*
- > Mechanical Tests
 - Physical dimensioning *(Method 2016)*
 - Marking: stamp or laser
 - Marking: resistance to solvents testing
(Method 2015)
 - Solderability *(Method 2003)*
 - Bond strength (destructive bond pull)
(Method 2011)
 - Mechanical shock *(Method 2002)*
 - Vibration, variable frequency *(Method 2007)*
 - Vibration random *(Method 2026)*
 - Constant acceleration (centrifuge)
(Method 2001)
 - Adhesion of lead finish *(Method 2025)*
 - Lead integrity *(Method 2004)*
 - Lead torque
 - Particle noise impact detection (PIND)
(Method 2020)
 - Bond shear
 - Die shear strength *(Method 2019)*
 - Lid torque for glass fit sealed packages
(Method 2024)
 - Visual per MIL-STD-883

- > Process testing
 - Latch up/electrical overload stress (EOS)
 - Electro static discharge (ESD) HMB,
MMB & CDM

ELECTRONIC DEVICE PHYSICAL EVALUATION AND ANALYSIS

- > BGA and uBGA automatic ball inspection
- > Bond pull
- > Die shear
- > Solder dip
- > Lead trim
- > Lead inspection and repair
- > Solderability restoration
- > Bake and dry pack

RELIABILITY ANALYSIS OR FAILURE ANALYSIS

- > Acoustic microscopy (CSAM)
- > Focus ion beam (FIB)
- > Scanning electron microscope (SEM)
- > X-ray
- > Real-time X-ray
- > Cross sectioning
- > Micro-probe
- > Light emission microscopy
- > De-cap (wet) manual/acid jet etcher
- > Construction analysis
- > Parallel polishing
- > Back lapping
- > Latch up/electrical overload stress (EOS)
- > Electro static discharge (ESD)
- > Level 1, 2 and 3 failure analysis
- > EDX
- > Digital image capture
- > Solderability testing

TAPE & REEL SERVICES

- > Tray to tape, QFP, TSOP, BGA, uBGA, FBGA, QFN
- > Tube to tape, SOIC, PLCC, SOJ, SOMC, SSOP, TSSOP, MSOP, VSOP, QSOP, QVSOP, DDPAK, DPAK, TO263, PLCC SOCKETS, MLF, MLP
- > Bulk to tape SOT, CHIP RESISTORS/CAPACITORS
- > Tray to tray
- > Tube to tube
- > Lead scan trays
- > Lead scan tubes
- > Satellite facilities available in some locations
- > 3-D laser scanning: QFP, TSOP, BGA and uBGA
- > 3-D vision system : SOIC, TSSOP, SSOP, MSOP, VSOP, QSOP, QVSOP, SOMC
- > 2-D: QFP, TSOP, PLCC, BGA and uBGA
- > Lead conditioning
- > In-line mark inspection
- > Parts marking
- > Tape custom packages (Criteria Labs will custom design tape pocket)
- > Bar coding and custom bar coding
- > Labeling and custom packaging
- > Laser mark capability
- > Detape
- > Bake and dry pack

QUALITY SYSTEMS

- > Total Quality Management Program
- > Incoming inspection of consigned and turnkey products
- > 100% ESD controlled environment
- > Packaging process to customer specifications
- > QA sample inspection or 100% based on customer requirements
- > SPC controlled in critical processes
- > 8D corrective action
- > Employee training and certification
- > Equipment calibration schedule
- > Document control
- > Final gate inspection (AQL or LTPD)
- > CFC and summary data reports

CERTIFICATIONS and COMPLIANCE PROCESSES

ISO-9001/2000
QML-PRF-38535 Certified
MIL-STD-883 Certified
IPC 610 Class I, II, III Certified
MIL-PRF-19500 Compliant
MIL-STD-750 Compliant
Classified Facility Controls
EIA 485 Compliant
EIA 481 Compliant



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